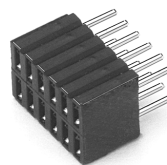
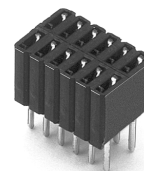
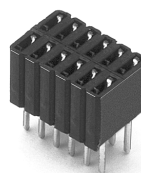


## Buchsenleisten RM 1,27 mm - 1-/2-reihig - Bauhöhe 4,6 mm

Female Header Strips - Pitch 1,27 mm - Single and Double Row - Height 4,6 mm

## Technische Daten / Technical Data:

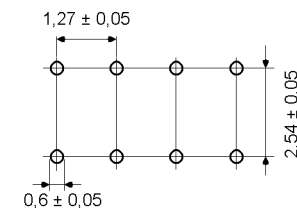
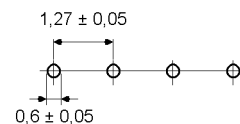
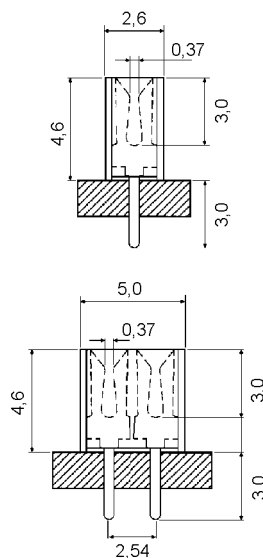
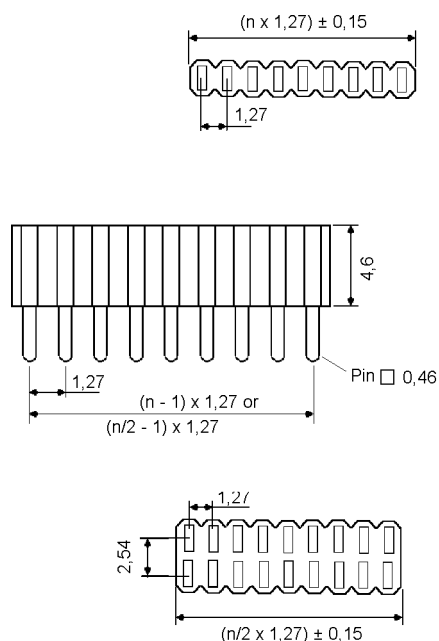
Isolierkörper <i>Insulator</i>	Thermoplastischer Kunststoff, nach UL94V0 <i>Thermoplastic, rated UL94V0</i>
Kontaktmaterial <i>Contact Material</i>	Kontakt CuZn 30 <i>Contact CuZn 30</i>
Kontaktoberfläche <i>Contact Surface</i>	lt. Oberflächenoptionen, über Ni (1,3-2,5 µm) <i>acc. to options (see below), over Ni (1,3-2,5 µm)</i>
Lötbarkeit <i>Solderability</i>	IEC512-12A <i>IEC512-12A</i>
Durchgangswiderstand <i>Contact Resistance</i>	≤ 20 mOhm <i>≤ 20 mOhm</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 10 <sup>9</sup> Ohm <i>&gt; 10<sup>9</sup> Ohm</i>
Spannungsfestigkeit <i>Test Voltage</i>	500 V <sub>AC</sub> <i>500 V<sub>AC</sub></i>
Nennstrom <i>Current Rating</i>	1 A <i>1 A</i>
Temperaturbereich <i>Temperature Range</i>	-40°C...+105°C <i>-40°C...+105°C</i>
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren; weitere Informationen in Kapitel T <i>Reflow-Soldering, further informations in chapter T</i>



© W+P PRODUCTS

B

Einsetzbar für Vierkantstift □ 0,46 mm  
Accepts square pin □ 0,46 mm



## PCB-Layout

n = Anzahl Kontakte  
n = No. of Contacts

Series	Contacts*	Rows*	Clip Plating*
709	002	1	00
	002-040-pol. einreihig single row 002-100-pol. zweireihig double row	1 = einreihig single row 2 = zweireihig double row	00 = vergoldet gold plated 60 = sel. Au/Sn duplex plating Au/Sn

(\* Bestellbeispiel - Bitte durch Ihre Spezifikationen ersetzen.)

\* Order example - To be replaced by your specifications.)

TEL.: +49 5223 98507-0  
FAX : +49 5223 98507-50

**W+P PRODUCTS**

E-MAIL: sales@wpro.com  
INTERNET: www.wpro.com

# Informationen zum Reflow-Lötverfahren

## Reflow-Soldering Informations

### Reflow-Lötverfahren Reflow-Soldering

Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Lötten im Reflowverfahren verarbeitet werden (Maximalwerte):

Profil Eigenschaft	Bleifreies Lötten
Durchschnitts-Ramp-Up Rate ( $T_{s_{max}}$ to $T_p$ )	3 °C / Sek. Max.
Vorheizen - Temperatur Min ( $T_{s_{min}}$ ) - Temperatur Max ( $T_{s_{max}}$ ) - Zeit ( $t_{s_{min}}$ auf $t_{s_{max}}$ )	150°C 200°C 60-180 Sekunden
Verbleiben oberhalb: - Temperatur ( $T_L$ ) - Zeit ( $t_L$ )	217°C 60-150 Sekunden
Peak/Klassifizierung Temperatur ( $T_p$ )	260°C +/- 5°C
Zeit innerhalb von 5°C um die Peak-Temperatur ( $t_p$ )	20-40 Sekunden
Ramp-Down Rate	6°C / Sekunde max.
Zeit von 25°C bis zur Peak-Temperatur	8 Minuten max.

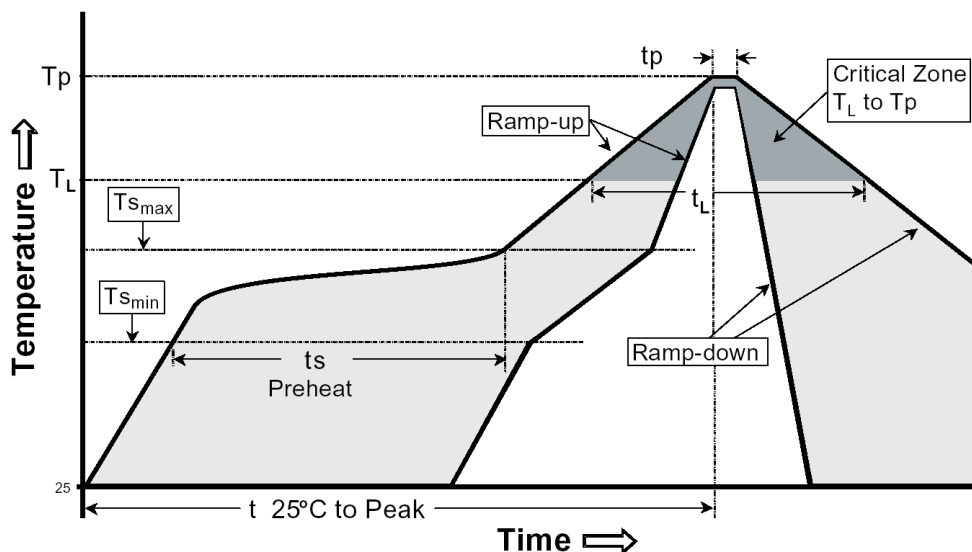
© W+P PRODUCTS

*Items should be soldered according to IPC/JEDEC J-STD-020C temperature-profile for leadfree reflow-soldering (maximum values):*

Profile Feature	PB-Free assembly
Average Ramp-Up Rate ( $T_{s_{max}}$ to $T_p$ )	3 °C / second max.
Preheat - Temperature Min ( $T_{s_{min}}$ ) - Temperature Max ( $T_{s_{max}}$ ) - Time ( $t_{s_{min}}$ to $t_{s_{max}}$ )	150°C 200°C 60-180 seconds
Time maintained above: - Temperature ( $T_L$ ) - Time ( $t_L$ )	217°C 60-150 seconds
Peak/Classification Temperature ( $T_p$ )	260°C +/- 5°C
Time within 5°C of actual Peak Temperature ( $t_p$ )	20-40 seconds
Ramp-Down Rate	6°C / second max.
Time 25°C to Peak Temperature	8 minutes max.

Empfohlenes Reflow-Lötprofil:

*Recommended Reflow-Soldering profile:*



T